Hiner-pack® MHWS Canister 300 mm

Safely protect and transport finished wafers in full, thin, or ultra-thin thicknesses

Wafers are the foundational building blocks of all modern electronic devices. Their significance lies in their role as the substrate on which integrated circuits (ICs) are fabricated, wafers are the core components of electronics. Not only wafers serve as the base material for manufacturing microchips. But also every processor, memory chip, sensor, and logic circuit begins as a wafer. Any high-end technology in any industry will use it, such as smartphones and computers to automobiles, medical devices, and industrial equipment. Wafers are to electronics what DNA is to life—a core substrate that defines how technology functions, evolves, and connects the modern world.

Therefore, the protection and transportation of the wafers will become particularly important.

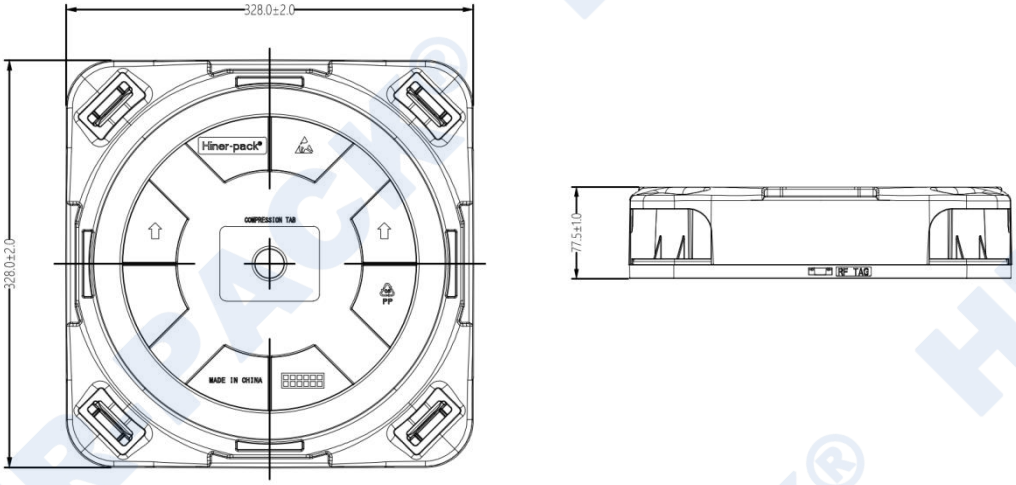
SPECIFICATIONS

- 328 mm L × 328 mm W × 77.5 mm H (12.91" × 12.91" × 3.05")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (5)

FEATURES & BENEFITS

- Protect wafers from contamination (e.g., particles, moisture, and chemicals)
- Prevent mechanical damage (e.g., scratches, breakage)
- Maintain cleanliness in cleanroom environments
- Ensure proper alignment and handling automation (e.g., by robotic wafer handlers)

DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MHWS-12/25-301/44	Bottom+Cushion+Interleaf+Top	300 mm

REFERENCE ILLUSTRATION

The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183-1 (23°C)	1.0 g/cm³
Melt Index (350°C/5kg)	ASTM D–1238	15.0 g/10min
Shrinkage Percentage	ISO 2577	1.2~1.6 %
Tensile Strength	ISO 527-2 (50mm/min)	25 MPa
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Strength (Fracture)	ISO 178 (2mm/min)	27 MPa
Flexural Modulus	ISO 178 (2mm/min)	1150 MPa
LZOD Notch Impact Strength (3.2mm)	ISO 180 (23°C)	30 kJ/m²
Surface Resistivity	ASTM D–257	1.0×10^{4}~1.0×10^{9} Ω/sq
Flame Retardant Rating	UL 94	HB Class

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.

Hiner-pack®

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